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March 6  
[Silicon Wafer Japan TC Chapter Meeting](#)

March 17  
[PV China TC Chapter Meeting](#)

March 30-April 2  
[North America Standards Spring 2015 Meetings](#)

[Full Calendar of Events](#)**From the Director's Desk**

James Amano  
Senior Director

***SEMI Standards - Setting the Foundation, Enabling Innovation***

Historically, some of the most significant documents developed by the SEMI Standards Program have focused on fundamental matters such as wafer dimensions and terminology, and as companies in our industry expand into emerging fields, they continue to realize the benefits of early standardization. Standards create the foundation that enables to innovate and develop new technologies and products, and move from the idea stage into high-volume manufacturing. A notable recent example of the key role that the SEMI Standards Program plays can be seen 3D-IC manufacturing, where the industry has come together to establish standards on processes, equipment, materials, and terminology.

Based on industry needs, [SEMI 3D2-1113, Specification for Glass Carrier Wafers for 3DS-IC Applications](#), was approved and published in late 2013 to provide the framework for ordering Glass Wafers for the application of carrier wafer for processing device wafers for 3D stacking. As this technology has developed, the requirements for such carrier wafers have become clearer and areas where 3D2 can be improved have been identified. Accordingly, the Bonded Wafer Stacks Task Force has commenced work on revising 3D2. The group intends to update (or eliminate) specifications that are unnecessarily stringent for 3D stacked applications and add additional glass types that were not included in 3D2 that are now seen as appropriate for industry requirements for 3D stacked applications. This ballot is scheduled to be issued to the global 3DS-IC Committee in Spring 2015 for adjudication at SEMICON West. [Read more...](#)

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**SEMI North America Standards 2015 Spring Meetings**

March 30-April 2  
San Jose, Santa Clara and Milpitas, California  
[Register Now!](#)

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